

3rd International Conference on Electronic Circuits and Signaling Technologies

ICECST 2026

Organized by
Lincoln University College
Petaling Jaya, Malaysia



28-30, September 2026

 www.icecst.com

About the Conference

The 3rd International Conference on Electronic Circuits and Signaling Technologies [ICECST 2026] has been planned to highlight the rapidly emerging technologies related to advanced electronic circuits and signal processing technologies. The conference will provide an interdisciplinary platform for researchers to present and discuss about the state-of-the-art research innovations, trends, and challenges encountered and solutions adopted in the fields of intelligent electronic circuits and signal processing technologies. The signals, communications and embedded domain covers the analog and digital signals and systems and embedded system by using the analytical and digital tools for the analysis of deterministic signals and applications to digital signal processing and digital/analog communications. The 3rd International Conference on Electronic Circuits and Signaling Technologies [ICECST 2026] is proud to host a global gathering of novel research expertise in advanced characterization techniques in the highly complex field of signal processing and information communications, which brings together researchers, practitioners, and scientists to discuss about the latest methods, research developments, and future opportunities. Moreover, ICECST 2026 has been designed to leverage a unique opportunity to gain state-of-the-art research insights through knowledge exchange on the convergence between the smart and advanced Electronic Circuits and Signaling Technologies.

About the College

Lincoln University College (LUC), located at Petaling Jaya, Malaysia was established in the year 2002 as Lincoln College (LC) and later upgraded to Lincoln University College in the year 2011. Lincoln University College is one of the premier private institutions of higher education approved by the Ministry of Higher Education and Malaysian Qualifications Agency (MQA- National Accreditation Board). The University College is also crowned with 5 Star ranking by the Ministry of Higher Education, Malaysia in 2017. Lincoln University College is listed among the top nine Malaysian universities according to the Times Higher Education (THE) University Impact Rankings 2019. LUC is also an ISO 9001:2015 certified academic institution. Lincoln University College is also the associate member of the 'Association of Indian Universities (AIU)', Association of Commonwealth Universities (ACU), London and a member of 'International Association of Universities (IAU)', Paris.

Call for Papers

Circuits and Embedded Systems

- Digital Circuits and FPGA based Designs
- Memory Circuits and System Design
- Wearable Electronics and Sensors
- MEMS/NEMS Devices and Applications
- Nanophotonics, Nanoelectronics and Hybrid Platforms
- Semiconducting Electronic Material and Devices
- Sustainable Electronic Design
- Circuit Reliability and Fault Tolerance
- Computer Aided Design and Verification
- Device Technology, Modeling and Simulation
- Embedded for IoT and Signal Processing Models
- Embedded for AI, ML, and Future Technologies
- Emerging CMOS Technologies
- Microsystems
- Sensors and Sensing Systems
- Biomedical and Bio-inspired Systems
- VLSI Systems and Applications
- Networked Embedded Systems

Signal Processing Technologies

- Design and Implementation of Signal Processing Systems
- Novel Signal processing Theories and Methods
- Nonlinear Signal Processing
- Pattern Recognition, Analysis and Classification
- Optimization Techniques
- Speech and Language Processing
- Statistical Signal Processing
- Multimedia Signal Processing
- Multichannel Signal Processing
- Machine Learning/Deep Learning
- Signal Processing for VLSI
- Computer Vision and Robotics with Signal Processing Models
- Signal Processing Over Graphs and Networks
- Biomedical and Bio-Inspired Signal Processing
- Speech Information Processing: Recognition
- Diversity and Space-time Techniques

Manuscript Submission

All the manuscripts should be submitted via conference Email
icecst.conf@gmail.com in DOCX (WORD)/PDF as per the format.

For Online Submission - [Click here](#)

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All registered and presented papers will be submitted for inclusion into IEEE Xplore.

Author Ethics:

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Venue



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